



Title of Change:	Transfer of Automotive Assembly and Test operations of SMA packaged products to On Semiconductor Vietnam (OSV).
Proposed Changed Material First Ship Date:	01 October 2018
Current Material Last Order Date:	1 July 2018 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.
Current Material Last Delivery Date:	1 Oct 2018 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.
Product Category:	<i>Active components – Discrete components</i>
Contact information	Contact your local ON Semiconductor Sales Office or < Phuong.Hoang@onsemi.com >
Samples	Contact your local ON Semiconductor Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification.
Sample Availability Date:	1 July 2017
PPAP Availability Date:	31 July 2017
Additional Reliability Data	Contact your local ON Semiconductor Sales Office or < cheanching.sim@onsemi.com >.
Type of Notification	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and its conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com >.
Change Category	Type of Change
Process – Assembly	Move of all or part of assembly to a different location/site/subcontractor.
Process – Assembly	Change of product marking.
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor.
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.
Description and Purpose:	
<p>This Final Notification announces the transfer of Assembly and Test of SMA products from ON Semiconductor Malaysia (SBN) to ON Semiconductor Vietnam (OSV).</p> <p>Upon completion of this transfer, these SMA products will be sourced solely from OSV Vietnam locations using the same Bill of Material.</p> <p>ON Semiconductor Vietnam (OSV) is qualified site for SMA Standard discrete packaged products and is ISO TS16949 certified.</p> <p>Products sourced from OSV have been qualified to Automotive requirements and continue remain as Pb-free, Halide free and RoHS compliant.</p>	
Reason / Motivation for Change:	<ul style="list-style-type: none"> • Change benefits for customer(s): <ul style="list-style-type: none"> ○ Unconstrained Automotive Sourcing; Mfg floor space for future expansion ○ Sustained TS16949 Certification with the Same BOM / Equipment / Processes ○ Allow for increased support for Seremban packages that are currently constrained ○ OSV has been audited to VDA6.3 • Risks for delayed conversion: <ul style="list-style-type: none"> ○ No Seremban supply after July 1st, 2018 • Limited ability to support bridge build availability.



Anticipated impact on fit, form, function, reliability, product safety or manufacturability	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.
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Sites Affected:	
<input type="checkbox"/> All site(s)	<input type="checkbox"/> not applicable
<input checked="" type="checkbox"/> ON Semiconductor site(s): ON Seremban, Malaysia ON Dong Nai Province, Vietnam	<input type="checkbox"/> External Foundry/Subcon site(s)

Marking of Parts/ Traceability of Change:	Product from ON Semiconductor Vietnam (OSV) will be marked with site code "VN" prior to the date code while the Seremban device does not have site code marking.
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Reliability Data Summary:				
QV DEVICE NAME: 1SMA5945BT3G (Zener)				
PACKAGE: SMA				
Test	Specification	Condition	Interval	Result
HTRB	JESD22-A108	Ta = 150 °C, bias = 80% of rated V	1008 hrs	0/252
HTSL	JESD22-A103	Ta = 150 °C	1008 hrs	0/252
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, deltaTj=100°C max, Ton = Toff = 2min	15000 cyc	0/252
TC	JESD22-A104	Temp = -65°C to +150°C	1000 cyc	0/252
AC	JESD22-A102	121°C, 100% RH, 15psig, unbiased	96 hrs	0/252
H3TRB	JESD22-A101	Temp = 85°C, RH=85%, bias = 80% of rated V	1008 hrs	0/252
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/1008
RSH	JESD22- B106	Ta = 265°C, 10 sec		0/90
SD	JSTD002	Ta = 245°C, 10 sec		0/45
Note: AEC-1 pager is attached.				
To access file attachments on pdf copy of PCN, please be guided by the steps below:				
1. Download pdf copy of the PCN to your computer				
2. Open the downloaded pdf copy of the PCN				
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field				
4. Then click on the attached file/s				

Electrical Characteristic Summary: Electrical characteristics are not impacted.



List of Affected Standard Parts:

Current SBN Part Number	Qualification Vehicle
SZ1SMA5913BT3G	
SZ1SMA5915BT3G	
SZ1SMA5916BT3G	
SZ1SMA5917BT3G	
SZ1SMA5918BT3G	
SZ1SMA5919BT3G	
SZ1SMA5920BT3G	
SZ1SMA5921BT3G	
SZ1SMA5922BT3G	
SZ1SMA5923BT3G	
SZ1SMA5924BT3G	
SZ1SMA5925BT3G	
SZ1SMA5926BT3G	1SMA5945BT3G
SZ1SMA5927BT3G	
SZ1SMA5928BT3G	
SZ1SMA5929BT3G	
SZ1SMA5930BT3G	
SZ1SMA5931BT3G	
SZ1SMA5932BT3G	
SZ1SMA5933BT3G	
SZ1SMA5934BT3G	
SZ1SMA5936BT3G	
SZ1SMA5937BT3G	
SZ1SMA5938BT3G	
SZ1SMA5939BT3G	
SZ1SMA5940BT3G	
SZ1SMA5941BT3G	
SZ1SMA5942BT3G	
SZ1SMA5943BT3G	
SZ1SMA5945BT3G	